



September 28, 2001 ATTORNEY'S DOCKET NO. 97-064B



Box Patent Application
Assistant Commissioner for Patents
Washington, DC 20231

Sir:

Please file the divisional patent application of *Matthew G. Kistner and Jeff D.*Will for Combined Superplastic Forming and Adhesive Bonding, which is based upon

U.S. Patent Application 09/556,752, filed April 21, 2000, and U.S. Provisional Patent

Application 60/130,869, filed April 23, 1999. To support the filing, please find enclosed:

The application including twenty-seven (27) written pages and two (2) sheets of drawing;

A copy of the original declaration from 09/556,752; and A postcard for you to acknowledge receipt.

The filing fee is calculated as follows:

| CLAIMS AS FILED | | | | |
|--------------------|--------------|--------------|---------|-----------------|
| FOR | NUMBER FILED | NUMBER EXTRA | RATE | FEE |
| TOTAL CLAIMS | 6 | 0 | \$18.00 | \$0.00 |
| INDEPENDENT CLAIMS | 2 | 0 | \$80.00 | \$0.00 |
| BASIC FEE | | | | <u>\$710.00</u> |
| | | TOTAL FIL | ING FEE | \$710.00 |

Please charge Deposit Account No. 02-2960 in the amount of \$710.00. The Commissioner is authorized to charge any additional fees under 37 CFR § 1.16 or § 1.17 that may be required at any time during the prosecution of this application 766328

without specific authorization, or credit any overpulment to Deposit Account 02-2960. Any necessary duplicate copies of this letter are enclosed.

The parent application was assigned of record to The Boeing Company at Reel 011176, Frame 0254.

Please address future correspondence to:

John C. Hammar The Boeing Company PO BOX 3707, MC 13-08 Seattle, WA 98124-2707

Respectfully,

John C. Hammar

Registration No.: 29,928

206-544-1059

Enclosures: application

declaration from 09/556,752

return postcard